

This IC is used for secondary protection of lithium-ion rechargeable batteries, and incorporates high-accuracy voltage detection circuits and delay circuits. The S-82K3 Series enable connection of 3-serial cell, and the S-82K4 Series enable connection of 4-serial cell.

This IC provides a wake-up function to prevent the fuse from blowing during battery connection, and allows the lithium battery to be connected in any order.

Since this IC also comes with a constant voltage output circuit, it can be used as a constant-voltage power supply for an external RTC (Real-Time clock IC).

■ Features

- High-accuracy voltage detection circuit for each cell

Overcharge detection voltage n	3.600 V to 4.800 V (5 mV step)	Accuracy ± 15 mV ($T_a = +25^\circ\text{C}$)
		Accuracy ± 20 mV ($T_a = -10^\circ\text{C}$ to $+60^\circ\text{C}$)
Overcharge release voltage n*1	3.600 V to 4.800 V	Accuracy ± 50 mV
VRTC pin shutdown voltage n	2.500 V to 2.800 V (100 mV step)	Accuracy ± 50 mV
- The wake-up function monitoring battery connection prevents CO pin output errors during battery connection
- Delay times for overcharge detection are generated only by an internal circuit (external capacitors are unnecessary)

Overcharge detection delay time, VRTC pin shutdown delay time:	1 s, 2 s, 4 s, 6 s
Overcharge timer reset function:	Available, unavailable
- CO pin output voltage is limited to 7.5 V max.
- VRTC pin output voltage: 1.800 V to 3.300 V (100 mV step) Accuracy $\pm 2\%$ ($T_a = +25^\circ\text{C}$)
- VRTC pin output current: 2 mA max.
- Wide operation temperature range: $T_a = -40^\circ\text{C}$ to $+85^\circ\text{C}$
- Low current consumption

During operation ($V_{\text{CU}} - 1.0$ V for each cell):	4.0 μA max.
During VRTC pin shutdown ($V_{\text{RSD}} - 1.0$ V for each cell):	1.0 μA max.
- Lead-free (Sn 100%), halogen-free

*1. Overcharge release voltage = Overcharge detection voltage – Overcharge hysteresis voltage
(Overcharge hysteresis voltage can be selected from a range of 0 mV to 400 mV in 50 mV step.)

Remark n = 1, 2, 3, 4

■ Application

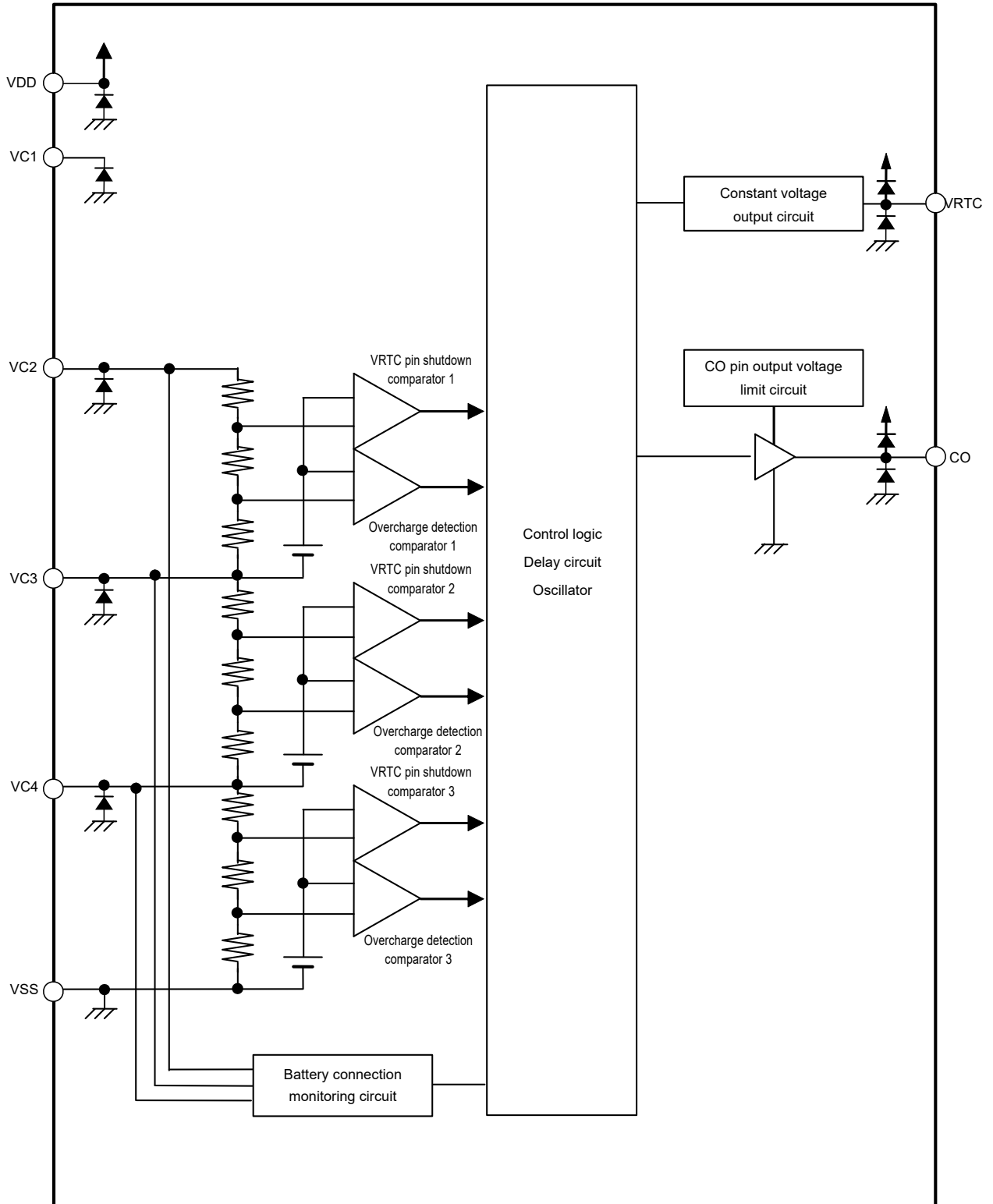
- Lithium-ion rechargeable battery packs (for secondary protection)

■ Packages

- DFN-8(2020)A
- HSNT-8(1616) (Under development)

■ **Block Diagrams**

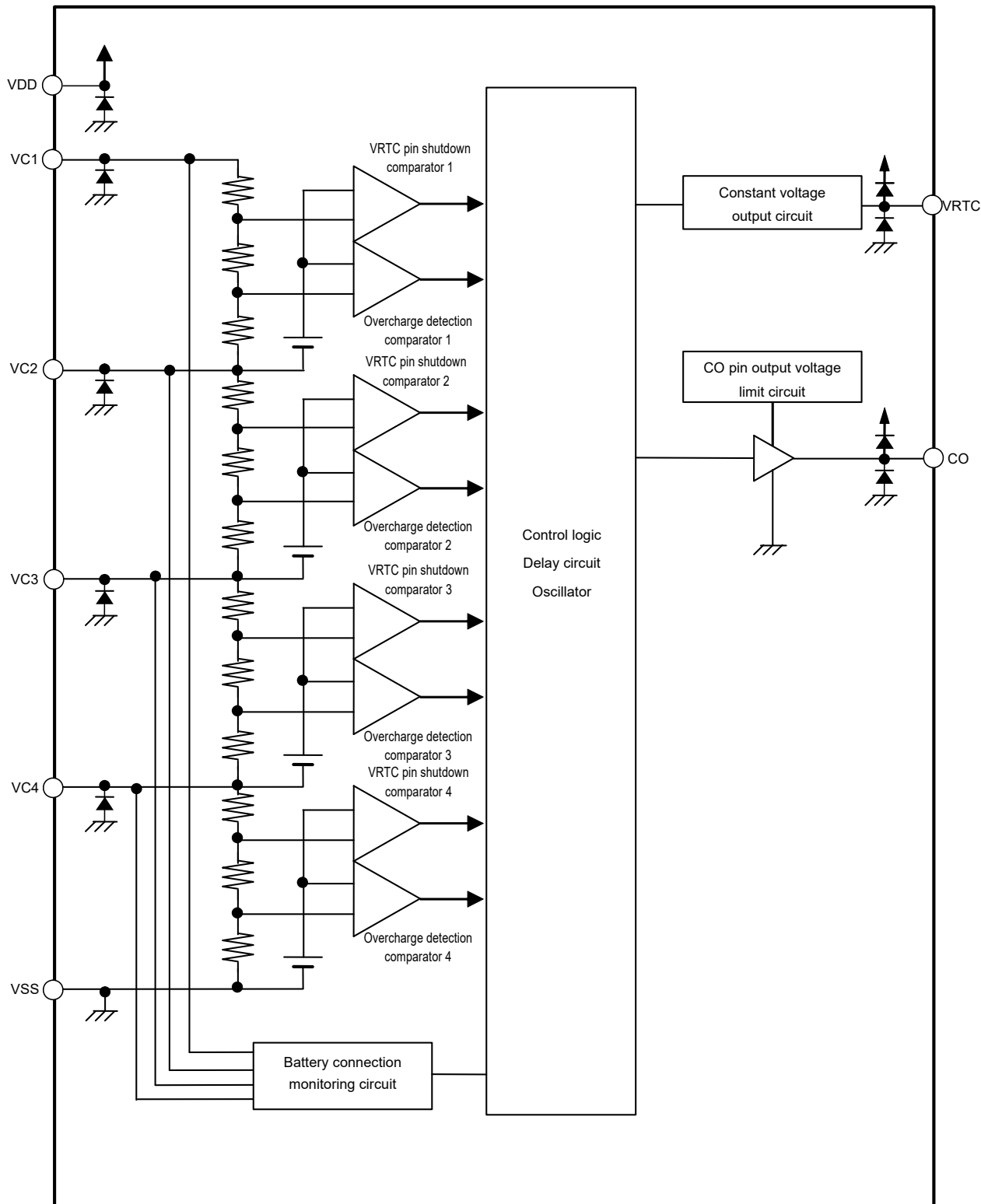
1. **S-82K3 Series**



Remark Diodes in the figure are parasitic diodes.

Figure 1

2. S-82K4 Series

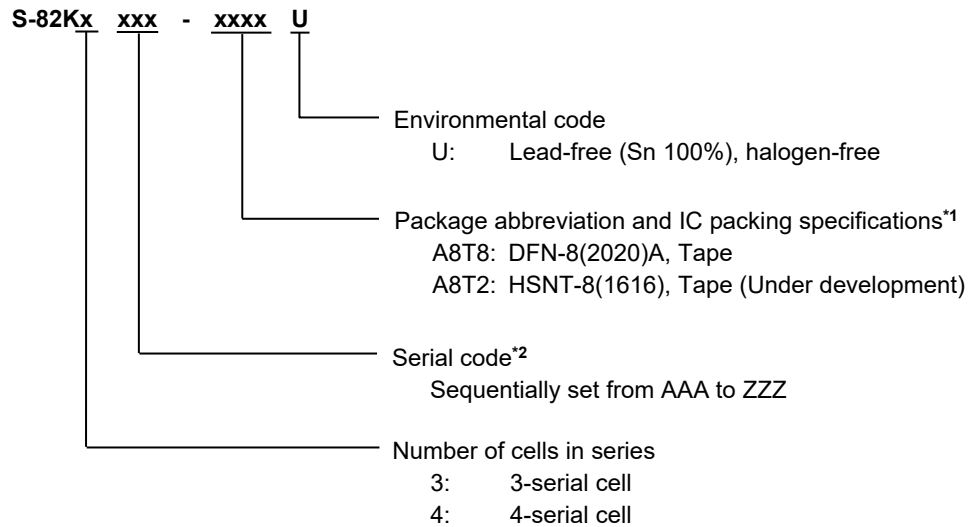


Remark Diodes in the figure are parasitic diodes.

Figure 2

■ **Product Name Structure**

1. Product name



*1. Refer to the tape drawing.
 *2. Refer to "3. Product name list".

2. Packages

Table 1 Package Drawing Codes

Package Name	Dimension	Tape	Reel	Land
DFN-8(2020)A	IB008-A-P-SD	IB008-A-C-SD	IB008-A-R-SD	IB008-A-L-SD
HSNT-8(1616)	PY008-A-P-SD	PY008-A-C-SD	PY008-A-R-SD	PY008-A-L-SD

3. Product name list

3.1 S-82K3 Series

3.1.1 DFN-8(2020)A

Table 2

Product Name	Overcharge Detection Voltage [V _{CU}]	Overcharge Release Voltage [V _{CL}]	VRTC Pin Output Voltage [V _{VRTC}]	VRTC Pin Shutdown Voltage [V _{RS} D]	VRTC Pin Recovery Voltage [V _{RST}]	Overcharge Detection Delay Time* ¹ [t _{CU}]	VRTC Pin Shutdown Delay Time* ¹ [t _{RS} D]	Overcharge Timer Reset Function* ²
S-82K3AAA-A8T8U	4.600 V	4.300 V	3.300 V	2.500 V	2.700 V	6 s	6 s	Unavailable
S-82K3AAB-A8T8U	4.550 V	4.300 V	3.300 V	2.500 V	2.700 V	6 s	6 s	Unavailable

*1. Overcharge detection delay time, VRTC pin shutdown delay time: 1 s, 2 s, 4 s, 6 s

*2. Overcharge timer reset function: Available, unavailable

Remark Please contact our sales representatives for products other than the above.

3.2 S-82K4 Series

3.2.1 DFN-8(2020)A

Table 3

Product Name	Overcharge Detection Voltage [V _{CU}]	Overcharge Release Voltage [V _{CL}]	VRTC Pin Output Voltage [V _{VRTC}]	VRTC Pin Shutdown Voltage [V _{RS} D]	VRTC Pin Recovery Voltage [V _{RST}]	Overcharge Detection Delay Time* ¹ [t _{CU}]	VRTC Pin Shutdown Delay Time* ¹ [t _{RS} D]	Overcharge Timer Reset Function* ²
S-82K4AAA-A8T8U	4.600 V	4.300 V	3.300 V	2.500 V	2.700 V	6 s	6 s	Unavailable
S-82K4AAB-A8T8U	4.550 V	4.300 V	3.300 V	2.500 V	2.700 V	6 s	6 s	Unavailable

*1. Overcharge detection delay time, VRTC pin shutdown delay time: 1 s, 2 s, 4 s, 6 s

*2. Overcharge timer reset function: Available, unavailable

Remark Please contact our sales representatives for products other than the above.

■ Pin Configuration

1. DFN-8(2020)A

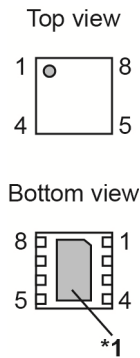


Figure 3

Table 4 S-82K3 Series

Pin No.	Symbol	Description
1	VDD	Positive power supply input pin
2	VC1	Positive power supply input pin
3	VC2	Positive voltage connection pin of battery 1
4	VC3	Negative voltage connection pin of battery 1 Positive voltage connection pin of battery 2
5	VC4	Negative voltage connection pin of battery 2 Positive voltage connection pin of battery 3
6	VSS	Negative power supply input pin Negative voltage connection pin of battery 3
7	CO	FET gate connection pin for charge control
8	VRTC	Voltage output pin for Real-time Clock (RTC)

Table 5 S-82K4Series

Pin No.	Symbol	Description
1	VDD	Positive power supply input pin
2	VC1	Positive power supply input pin Positive voltage connection pin of battery 1
3	VC2	Negative voltage connection pin of battery 1 Positive voltage connection pin of battery 2
4	VC3	Negative voltage connection pin of battery 2 Positive voltage connection pin of battery 3
5	VC4	Negative voltage connection pin of battery 3 Positive voltage connection pin of battery 4
6	VSS	Negative power supply input pin Negative voltage connection pin of battery 4
7	CO	FET gate connection pin for charge control
8	VRTC	Voltage output pin for Real-time Clock (RTC)

*1. Connect the heat sink of backside at shadowed area to the board, and set electric potential open or V_{C1}. However, do not use it as the function of electrode.

2. HSNT-8(1616)

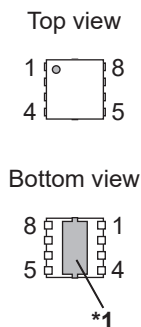


Figure 4

Table6 S-82K3 Series

Pin No.	Symbol	Description
1	VDD	Positive power supply input pin
2	VC1	Positive power supply input pin
3	VC2	Positive voltage connection pin of battery 1
4	VC3	Negative voltage connection pin of battery 1 Positive voltage connection pin of battery 2
5	VC4	Negative voltage connection pin of battery 2 Positive voltage connection pin of battery 3
6	VSS	Negative power supply input pin Negative voltage connection pin of battery 3
7	CO	FET gate connection pin for charge control
8	VRTC	Voltage output pin for Real-time Clock (RTC)

Table7 S-82K4 Series

Pin No.	Symbol	Description
1	VDD	Positive power supply input pin
2	VC1	Positive power supply input pin Positive voltage connection pin of battery 1
3	VC2	Negative voltage connection pin of battery 1 Positive voltage connection pin of battery 2
4	VC3	Negative voltage connection pin of battery 2 Positive voltage connection pin of battery 3
5	VC4	Negative voltage connection pin of battery 3 Positive voltage connection pin of battery 4
6	VSS	Negative power supply input pin Negative voltage connection pin of battery 4
7	CO	FET gate connection pin for charge control
8	VRTC	Voltage output pin for Real-time Clock (RTC)

*1. Connect the heat sink of backside at shadowed area to the board, and set electric potential open or V_{C1} . However, do not use it as the function of electrode.

■ Absolute Maximum Ratings

Table 8

(Ta = +25°C unless otherwise specified)

Item	Symbol	Applied Pin	Absolute Maximum Rating	Unit
Input voltage between VDD pin and VSS pin	V_{DS1}	VDD	$V_{SS} - 0.3$ to $V_{SS} + 28$	V
Input voltage between VC1 pin and VSS pin	V_{DS2}	VC1	$V_{SS} - 0.3$ to $V_{SS} + 28$	V
Input pin voltage	V_{IN}	VC2, VC3, VC4	$V_{SS} - 0.3$ to $V_{VC1} + 0.3$	V
CO pin output voltage	V_{CO}	CO	$V_{SS} - 0.3$ to $V_{DD} + 0.3$	V
VRTC pin output voltage	V_{VRTC}	VRTC	$V_{SS} - 0.3$ to $V_{SS} + 6$	V
Operation ambient temperature	T_{opr}	–	–40 to +85	°C
Storage temperature	T_{stg}	–	–40 to +125	°C

Caution The absolute maximum ratings are rated values exceeding which the product could suffer physical damage. These values must therefore not be exceeded under any conditions.

■ Thermal Resistance Value

Table 9

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	
Junction-to-ambient thermal resistance*1	θ_{JA}	DFN-8(2020)A	Board A	–	242	–	°C/W
			Board B	–	182	–	°C/W
			Board C	–	–	–	°C/W
			Board D	–	–	–	°C/W
			Board E	–	–	–	°C/W
		HSNT-8(1616)	Board A	–	214	–	°C/W
			Board B	–	172	–	°C/W
			Board C	–	–	–	°C/W
			Board D	–	–	–	°C/W
			Board E	–	–	–	°C/W

*1. Test environment: compliance with JEDEC STANDARD JESD51-2A

Remark Refer to "■ Power Dissipation" and "Test Board" for details.

■ Electrical Characteristics

Table 10

(Ta = +25°C unless otherwise specified)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Test Circuit
Detection Voltage							
Overcharge detection voltage n (n = 1, 2, 3, 4)	V _{CU_n}	Ta = +25°C	V _{CU} − 0.015	V _{CU}	V _{CU} + 0.015	V	1
		Ta = −10°C to +60°C*1	V _{CU} − 0.020	V _{CU}	V _{CU} + 0.020	V	1
Overcharge release voltage n (n = 1, 2, 3, 4)	V _{CL_n}	−	V _{CL} − 0.050	V _{CL}	V _{CL} + 0.050	V	1
VRTC pin shutdown voltage n (n = 1, 2, 3, 4)	V _{RSD_n}	−	V _{RSD} − 0.050	V _{RSD}	V _{RSD} + 0.050	V	1
VRTC pin recovery voltage n (n = 1, 2, 3, 4)	V _{RST_n}	−	V _{RST} − 0.100	V _{RST}	V _{RST} + 0.100	V	1
Input Voltage							
Operation voltage between VDD pin and VSS pin	V _{DSOP}	−	3.6	−	24	V	−
Output Voltage							
CO pin output voltage "H"	V _{COH}	−	4.0	6.0	7.5	V	1
Input Current							
Current consumption during operation	I _{OPE}	V1 = V2 = V3 = V4 = V _{CU} − 1.0 V	−	2.0	4.0	μA	1
Current consumption during VRTC pin shutdown	I _{OPED}	V1 = V2 = V3 = V4 = V _{RSD} − 1.0 V	−	−	1.0	μA	1
VC1 pin input current	I _{VC1}	V1 = V2 = V3 = V4 = V _{CU} − 1.0 V	−	−	3.7	μA	1
VCn pin input current (n = 2, 3, 4)	I _{VC_n}	V1 = V2 = V3 = V4 = V _{CU} − 1.0 V	−0.42	0	−	μA	1
Output Current							
CO pin source current	I _{COH}	−	−	−	−20	μA	1
CO pin sink current	I _{COL}	−	20	−	−	μA	1
Delay Time							
Overcharge detection delay time	t _{CU}	−	t _{CU} × 0.7	t _{CU}	t _{CU} × 1.3	s	1
Overcharge release delay time	t _{CL}	−	8	16	32	ms	1
Overcharge timer reset delay time	t _{TR}	With overcharge timer reset function	6	12	20	ms	−
Transition time to test mode	t _{TST}	−	−	−	10	ms	−
VRTC pin shutdown delay time	t _{RSD}	−	t _{RSD} × 0.7	t _{RSD}	t _{RSD} × 1.3	s	1
Wake-up delay time	t _{WU}	−	1	2	3	s	1
VRTC Pin Output							
VRTC pin output voltage	V _{VRTC}	I _{VRTC} = 10 μA, SW2 = ON	V _{VRTC} × 0.98	V _{VRTC}	V _{VRTC} × 1.02	V	1
VRTC pin output current	I _{VRTC}	−	−	−	2	mA	−

*1. Since products are not screened at high and low temperature, the specification for this temperature range is guaranteed by design, not tested in production.

■ **Test Circuit**

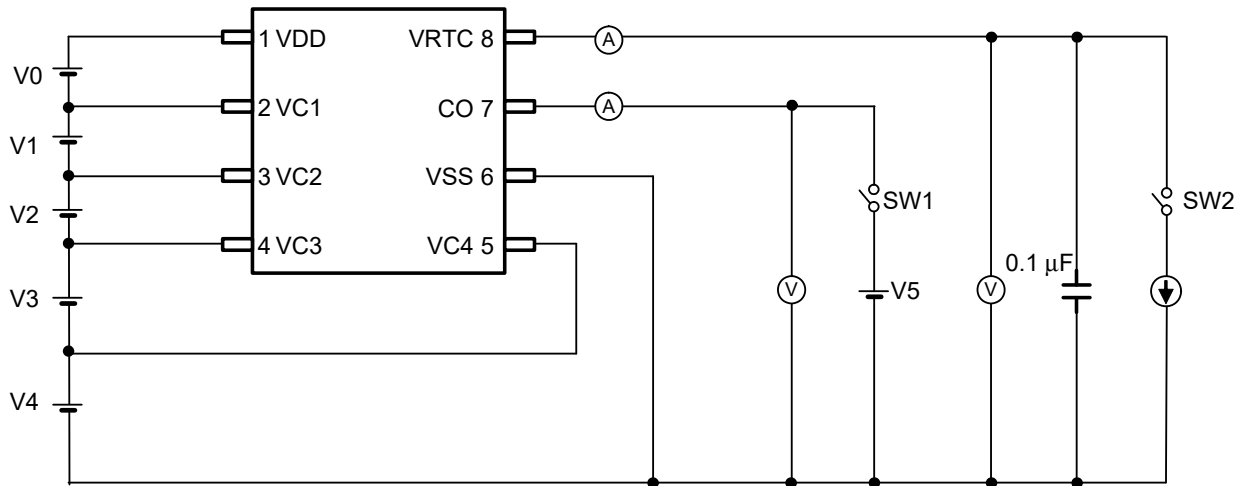


Figure 5 Test Circuit 1

In the initial status of the test circuit, SW1 and SW2 should be OFF.
 This section provides explanations of test items using test circuit 1.

1. Overcharge detection voltage n (V_{CU_n}), overcharge release voltage n (V_{CL_n})

After setting $V_0 = 0\text{ V}$, $V_1 = V_2 = V_3 = V_4 = V_{CU} - 0.1\text{ V}$, V_1 is gradually increased. When the CO pin output inverts, the voltage V_1 is defined as the overcharge detection voltage 1 (V_{CU1}). After that, V_1 is then set to $V_{CU} + 0.1\text{ V}$, $V_2 = V_3 = V_4 = 3.5\text{ V}$. V_1 is gradually decreased. When the CO pin output inverts again, the voltage V_1 is defined as the overcharge release voltage (V_{CL1}).

Overcharge detection voltage n (V_{CU_n}) and overcharge release voltage n (V_{CL_n}) can be determined in the same way as when $n = 1$.

2. VRTC pin shutdown voltage n (V_{RSD_n}), VRTC pin recovery voltage n (V_{RST_n})

After setting $V_0 = 0\text{ V}$, $V_1 = V_2 = V_3 = V_4 = 3.5\text{ V}$, V_1 is gradually decreased. When the VRTC pin output becomes V_{SS} , the voltage V_1 is defined as the VRTC pin shutdown voltage 1 (V_{RSD1}). After that, V_1 is then set to $V_{RSD} - 0.15\text{ V}$, $V_2 = V_3 = V_4 = 3.5\text{ V}$. V_1 is gradually increased. When the VRTC pin output voltage becomes the VRTC pin output voltage (V_{VRTC}), the voltage V_1 is defined as the VRTC pin recovery voltage 1 (V_{RST1}).

VRTC pin shutdown voltage n (V_{RSD_n}) and VRTC pin recovery voltage n (V_{RST_n}) can be determined in the same way as when $n = 1$.

3. CO pin output voltage "H" (V_{COH})

The CO pin output voltage "H" (V_{COH}) is the voltage between the CO pin and the VSS pin when $V_0 = 0\text{ V}$, $V_1 = 4.9\text{ V}$, $V_2 = V_3 = V_4 = 3.5\text{ V}$.

4. CO pin source current (I_{COH})

Set SW1 to ON after setting $V_0 = 0\text{ V}$, $V_1 = 4.9\text{ V}$, $V_2 = V_3 = V_4 = 3.5\text{ V}$, $V_5 = V_{COH} - 0.5\text{ V}$. The CO pin current is the CO pin source current (I_{COH}) at that time.

5. CO pin sink current (I_{COL})

Set SW1 to ON after setting $V_0 = 0\text{ V}$, $V_1 = V_2 = V_3 = V_4 = 3.5\text{ V}$, $V_5 = 0.5\text{ V}$. The CO pin current is the CO pin sink current (I_{COL}) at that time.

Remark $n = 1, 2, 3, 4$

6. Overcharge detection delay time (t_{CU}), overcharge release delay time (t_{CL})

After setting $V_0 = 0\text{ V}$, $V_1 = V_2 = V_3 = V_4 = 3.5\text{ V}$, V_1 is increased to 4.9 V . The overcharge detection delay time (t_{CU}) is the time period until the CO pin output inverts. After that, decrease V_1 to 3.5 V . The overcharge release delay time (t_{CL}) is the time period until the CO pin output inverts.

7. VRTC pin shutdown delay time (t_{RSD})

After setting $V_0 = 0\text{ V}$, $V_1 = V_2 = V_3 = V_4 = 3.5\text{ V}$, V_1 is decreased to 2.4 V . The VRTC pin shutdown delay time (t_{RSD}) is the time period until the VRTC pin output becomes V_{SS} .

■ Operation

Remark Refer to "■ Battery Protection IC Connection Examples".

1. Wake-up function operation during battery connection

The IC monitors whether or not all batteries have been connected to prevent CO pin output errors during battery connection from blowing the protection fuse. When all batteries have been connected, the IC transitions to the normal status. This is what we call the wake-up function. When 3.5 V or higher voltage batteries are connected to all battery connection pins and this state continues for at least the wake-up delay time (t_{WU}) = 2.0 s typ., the VRTC pin outputs the VRTC pin output voltage (V_{VRTC}) and the device enters the normal status.

No other operations are possible until the IC is in the normal status. The wake-up function is disabled when the IC enters the normal status and is enabled access to other operations.

2. Normal status

When all battery voltages are higher than the VRTC pin shutdown voltage n (V_{RSDn}) but lower than overcharge detection voltage n (V_{CUn}), the CO pin outputs "L" and the VRTC pin outputs V_{VRTC} . This status is called the normal status.

3. Overcharge status

When the voltage of any of all batteries exceeds the overcharge detection voltage n (V_{CUn}) and this condition continues for the overcharge detection delay time (t_{CU}) or longer, the CO pin output inverts. This status is called the overcharge status. Charge control and secondary protection can be enabled by connecting an FET to the CO pin.

When all battery voltages fall below the overcharge release voltage (V_{CLn}) and this condition continues for the overcharge release delay time (t_{CL}) or longer, this IC returns to the normal status.

4. VRTC pin shutdown status

When the voltage of any of the batteries falls below the VRTC pin shutdown voltage n (V_{RSDn}) and this condition continues for the VRTC pin shutdown delay time (t_{RSD}) or longer, the VRTC pin output becomes V_{SS} . This status is called the VRTC pin shutdown status.

When all battery voltages exceed the VRTC pin recovery voltage n (V_{RSTn}), this IC returns to the normal status.

5. Overcharge timer reset function

During t_{CU} , which is from when the voltage of any of the batteries being charged exceeds V_{CUn} until charging stops, this IC has the following operations.

Even if an overcharge release noise, which temporarily forces the battery voltage below V_{CUn} , is input, t_{CU} is continuously counted as long as the overcharge release noise time is shorter than the overcharge timer reset delay time (t_{TR}). Under the same conditions, if the overcharge release noise time is t_{TR} or longer, counting of t_{CU} is reset once. After that, when V_{CUn} has been exceeded, counting of t_{CU} resumes.

Remark $n = 1, 2, 3, 4$

6. Test mode

In this IC, the overcharge detection delay time (t_{cu}) and VRTC pin shutdown delay time (t_{rSD}) can be shortened by entering the test mode.

The test mode can be set by retaining the VDD pin voltage 7.0 V or higher than the VC1 pin voltage for at least 10 ms ($V1 = V2 = V3 = V4 = 3.5\text{ V}$, $T_a = +25^\circ\text{C}$). The status is retained by the internal latch and the test mode is retained even if the VDD pin voltage is decreased to the same voltage as that of the VC1 pin.

When this IC becomes the detection status after the delay time following the detection of an overcharge or VRTC pin shutdown has elapsed, the latch for retaining the test mode is reset and this IC is released from the test mode.

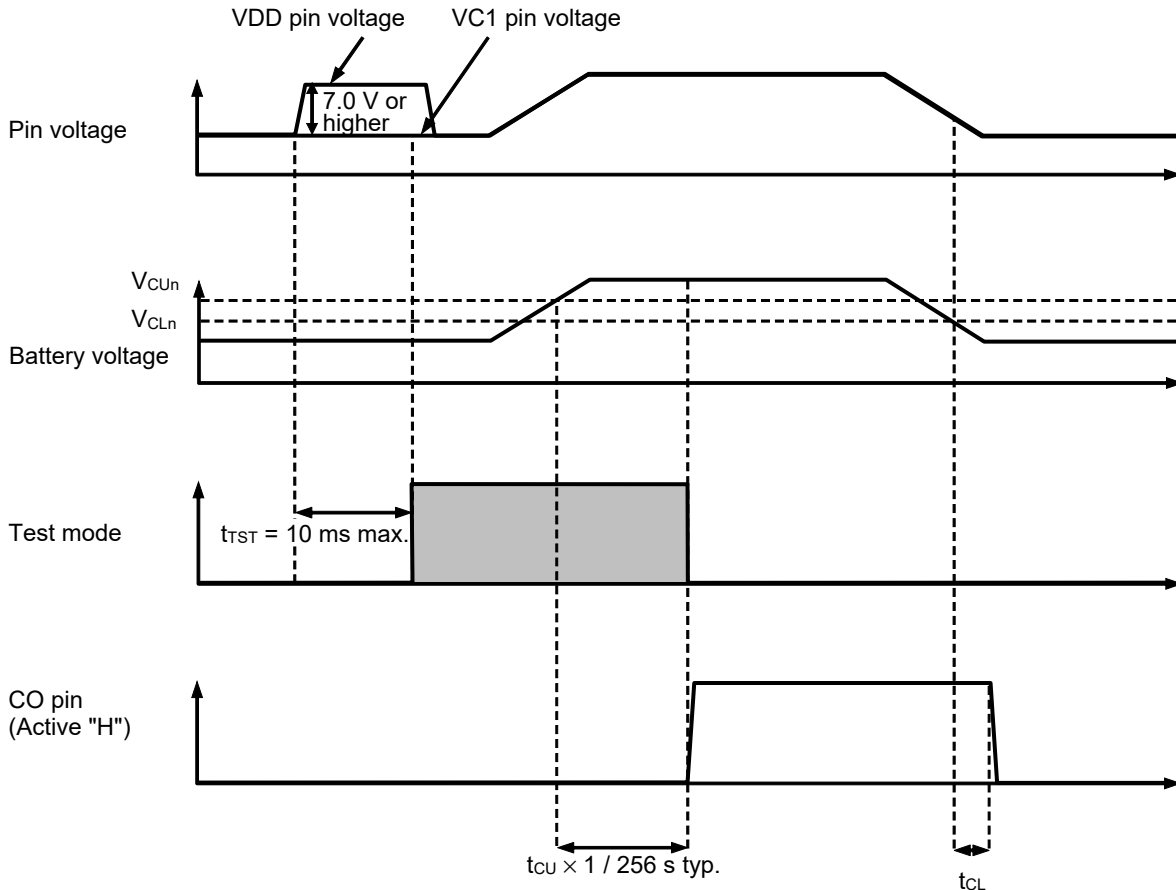


Figure 6

- Caution**
1. Set the test mode when no batteries are overcharged.
 2. The overcharge timer reset delay time (t_{TR}) is not shortened in the test mode.

Remark n = 1, 2, 3, 4

■ **Timing Charts**

1. **Wake-up function operation during battery connection (S-82K4 Series)**

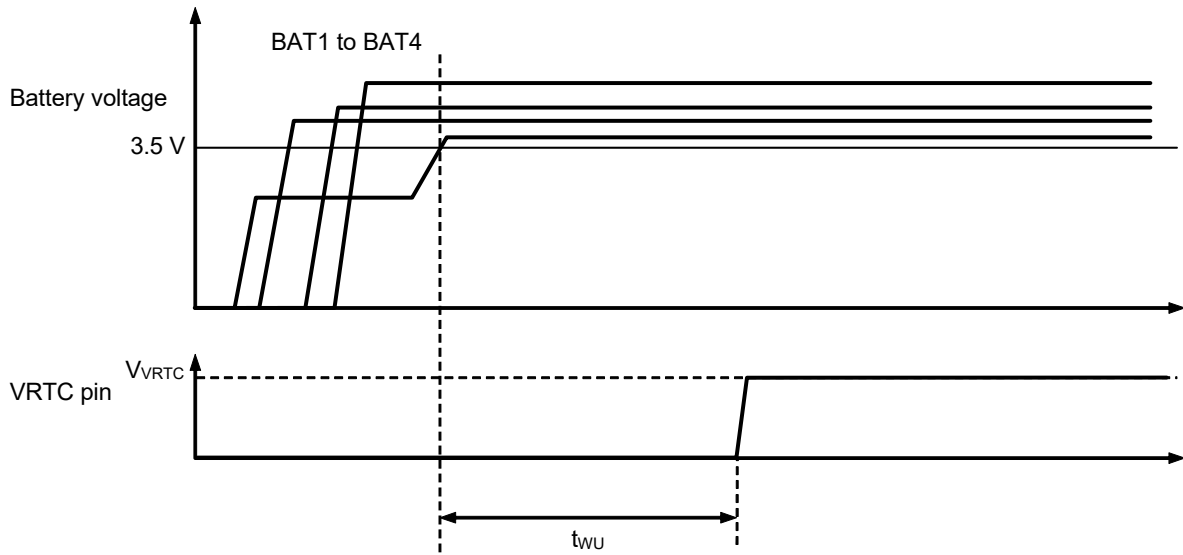


Figure 7

2. Overcharge detection operation (With overcharge timer reset function)

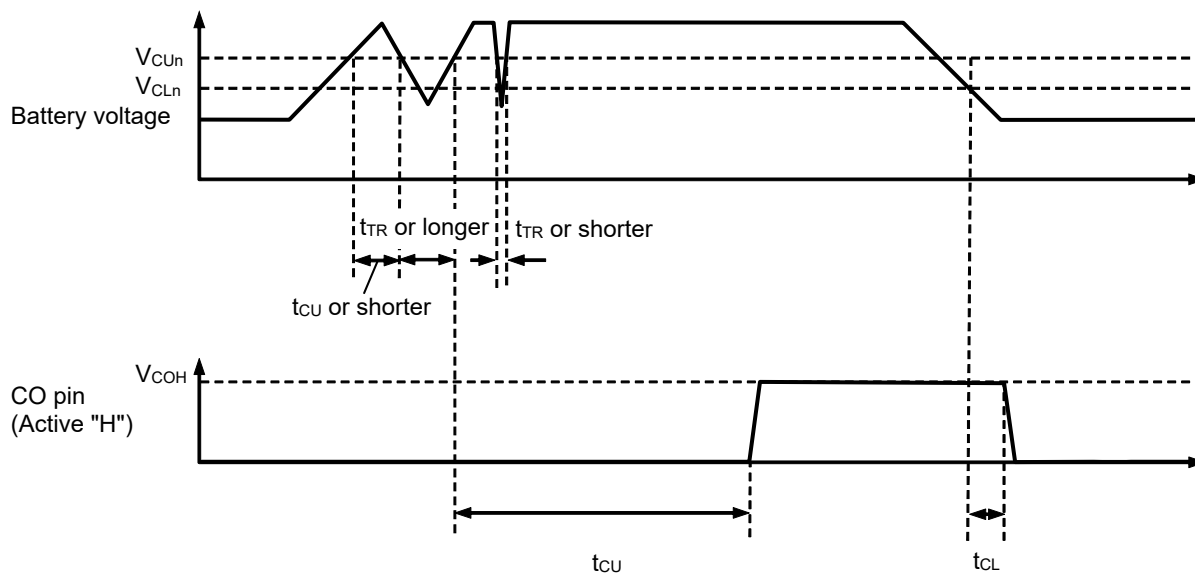


Figure 8

Remark n = 1, 2, 3, 4

3. VRTC pin shutdown operation

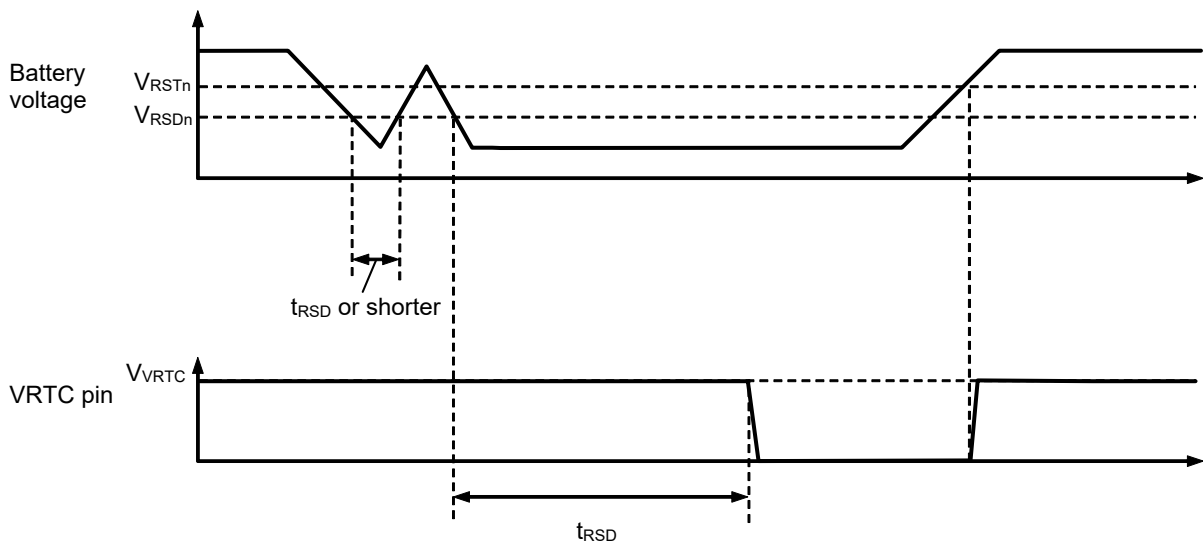


Figure 9

Remark n = 1, 2, 3, 4

4. Overcharge timer reset operation (With overcharge timer reset function)

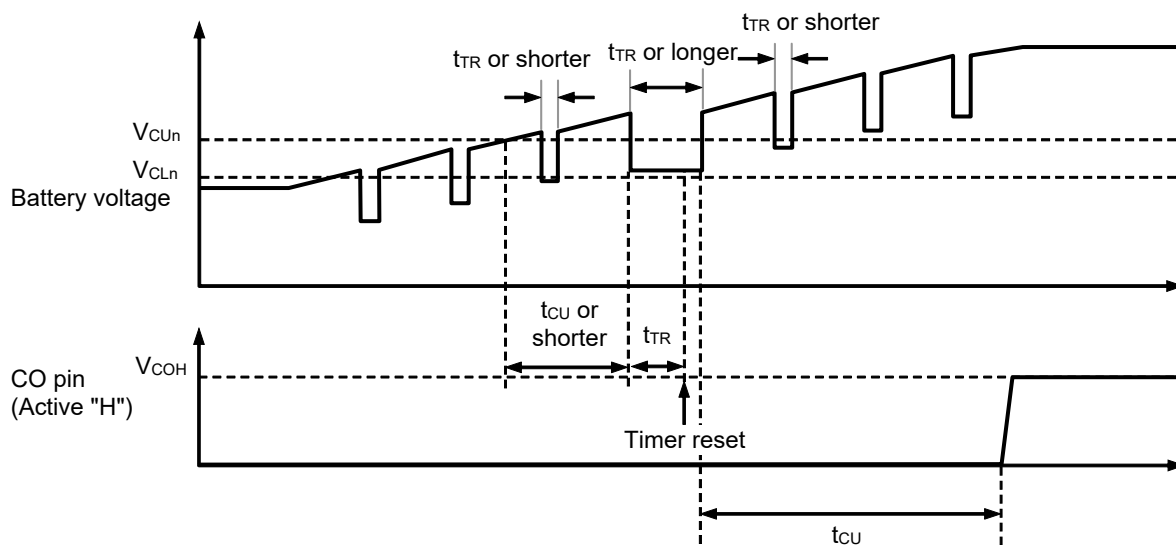
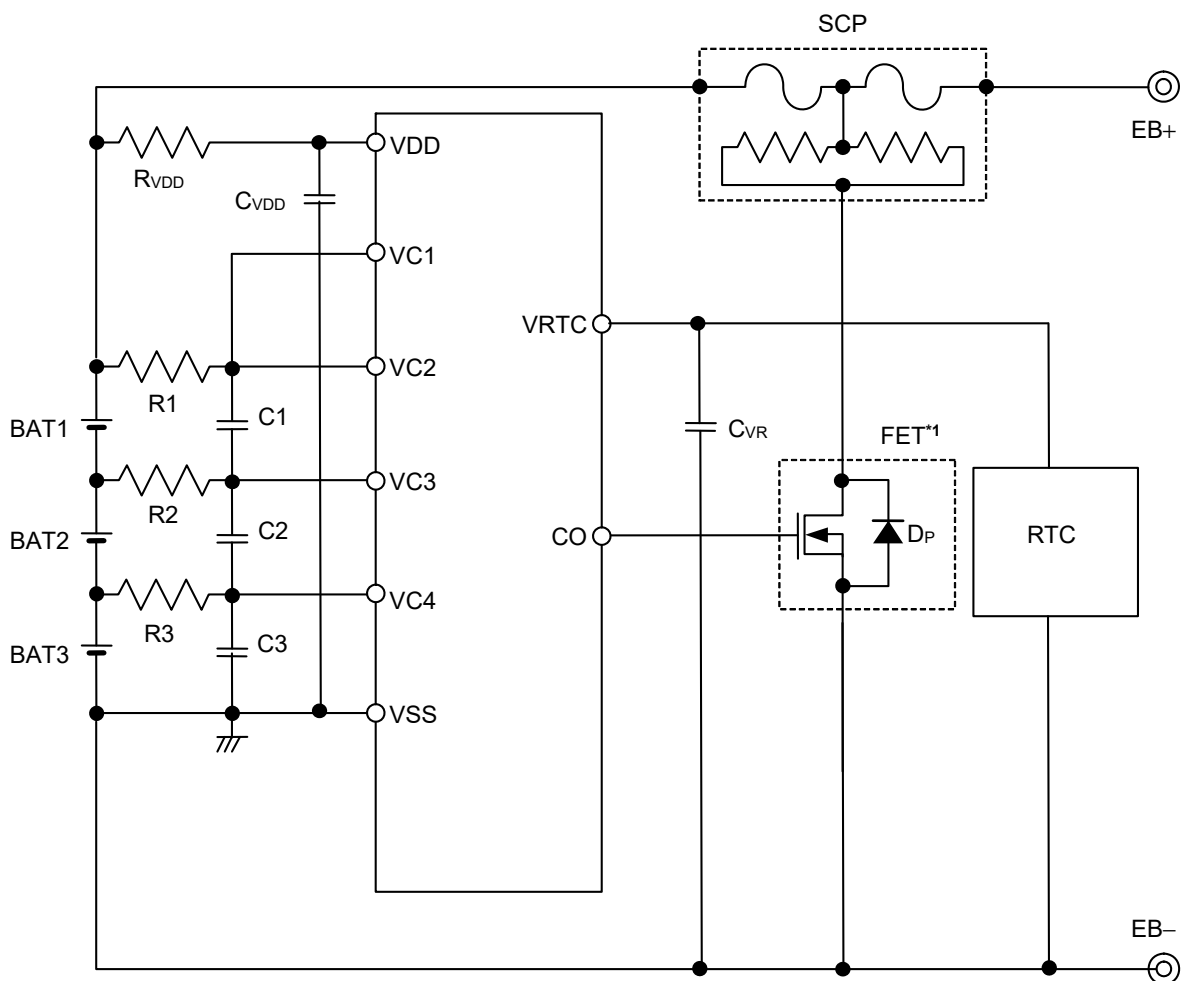


Figure 10

Remark n = 1, 2, 3, 4

■ **Battery Protection IC Connection Examples**

1. **S-82K3 Series (3-serial cell)**



*1. This IC limits its CO pin output voltage to 7.5 V max., so a FET with the gate withstand voltage of 8 V can be used.

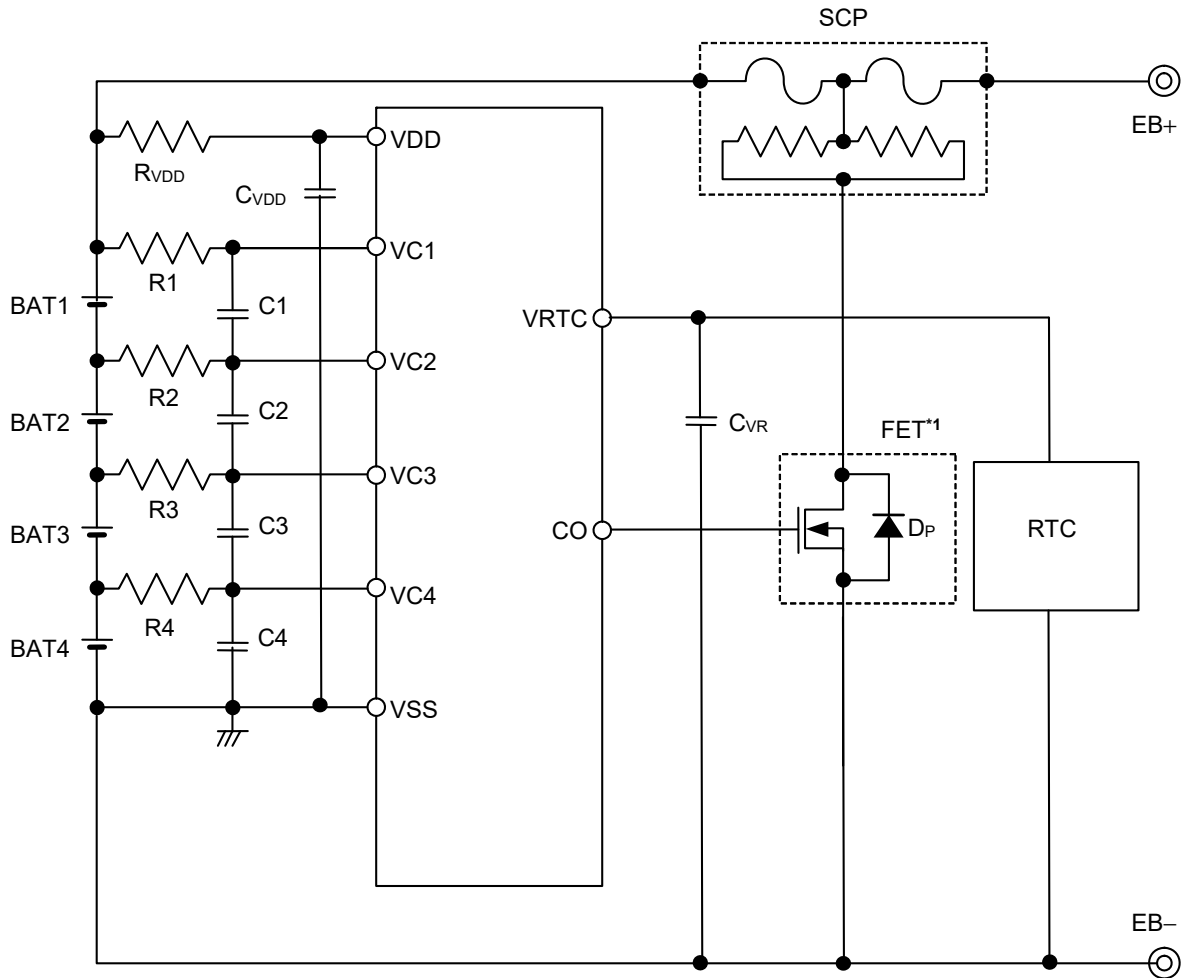
Figure 11

Table 11 Constants for External Components

No.	Part	Min.	Typ.	Max.	Unit
1	R1 to R3	1	1	1	kΩ
2	C1 to C3, C _{VDD}	0.1	0.1	1	μF
3	R _{VDD}	100	100	1000	Ω
4	C _{VR}	—	0.1	—	μF

- Caution**
1. The constants may be changed without notice.
 2. It has not been confirmed whether the operation is normal or not in circuits other than the connection examples. In addition, the connection examples and the constants do not guarantee proper operation. Perform thorough evaluation using the actual application to set the constants.
 3. Set the same constants to R1 to R3 and to C1 to C3 and C_{VDD}.

2. S-82K4 Series (4-serial cell)



*1. This IC limits its CO pin output voltage to 7.5 V max., so a FET with the gate withstand voltage of 8 V can be used.

Figure 12

Table 12 Constants for External Components

No.	Part	Min.	Typ.	Max.	Unit
1	R1 to R4	1	1	1	kΩ
2	C1 to C4, CvDD	0.1	0.1	1	μF
3	RvDD	100	100	1000	Ω
4	CvR	—	0.1	—	μF

- Caution**
1. The constants may be changed without notice.
 2. It has not been confirmed whether the operation is normal or not in circuits other than the connection examples. In addition, the connection examples and the constants do not guarantee proper operation. Perform thorough evaluation using the actual application to set the constants.
 3. Set the same constants to R1 to R4 and to C1 to C4 and CvDD.

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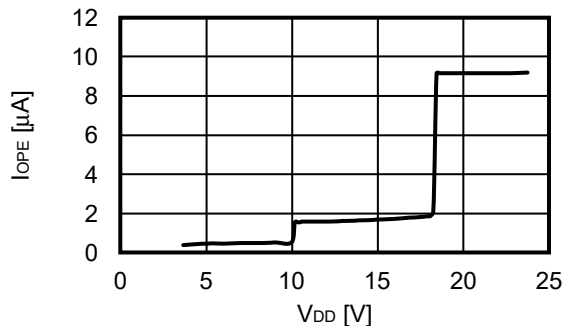
■ Precaution

- Before the battery connection, short-circuit the battery side pins R_{VDD} and R1, shown in the figures in "■ **Battery Protection IC Connection Examples**".
- The application conditions for the input voltage, output voltage, and load current should not exceed the power dissipation.
- Do not apply to this IC an electrostatic discharge that exceeds the performance ratings of the built-in electrostatic protection circuit.
- ABLIC Inc. claims no responsibility for any disputes arising out of or in connection with any infringement of patents owned by a third party by products including this IC.

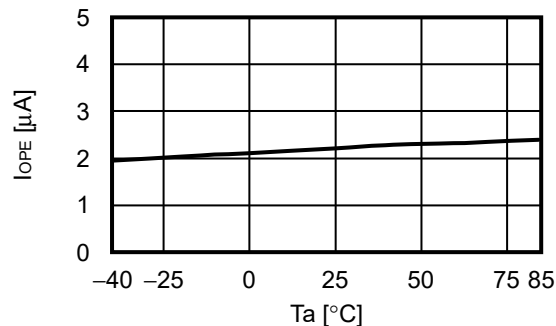
■ Characteristics (Typical Data)

1. Current consumption

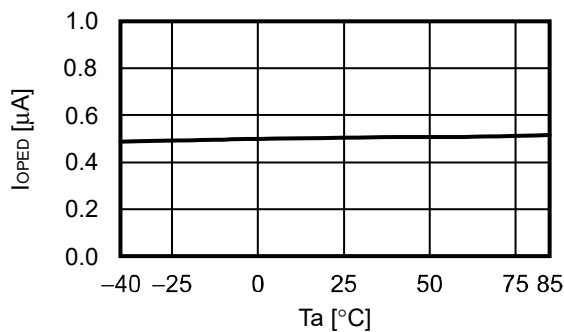
1. 1 I_{OPE} vs. V_{DD}



1. 2 I_{OPE} vs. T_a

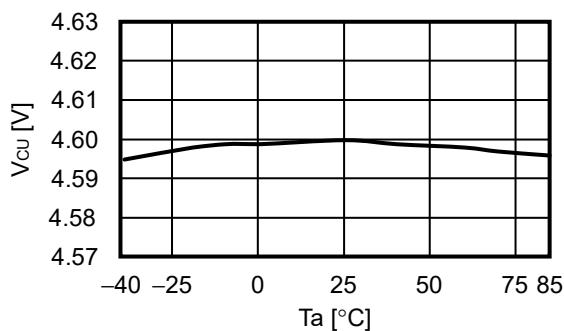


1. 3 I_{OPED} vs. T_a

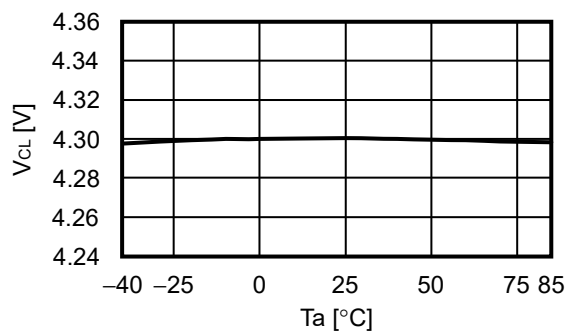


2. Detection voltage, release voltage

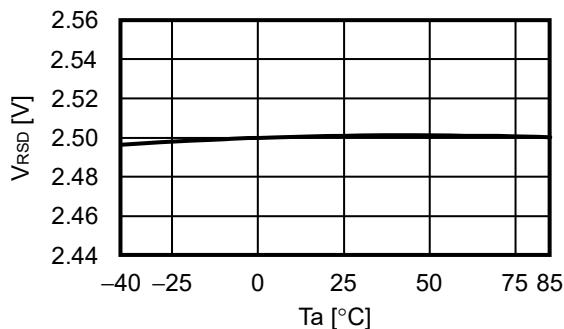
2. 1 V_{CU} vs. T_a



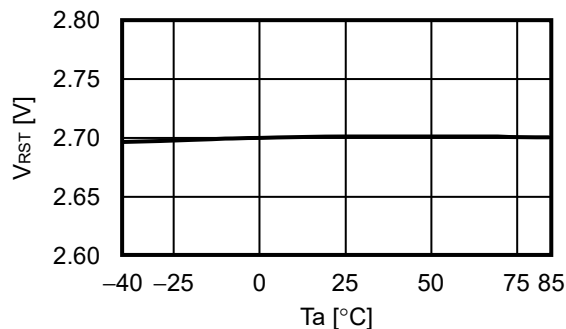
2. 2 V_{CL} vs. T_a



2. 3 V_{RSD} vs. T_a

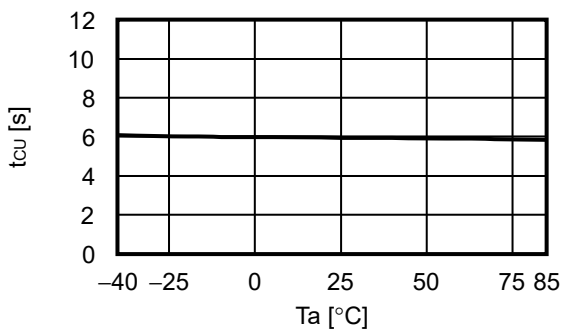


2. 4 V_{RST} vs. T_a

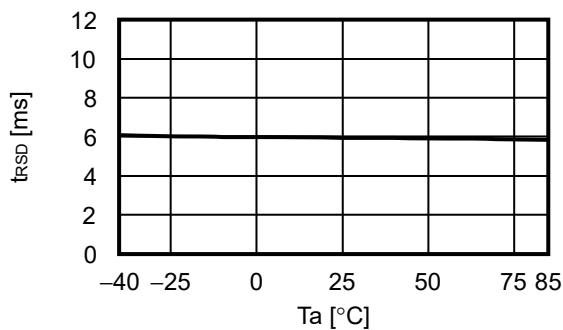


3. Delay time

3.1 t_{CU} vs. T_a

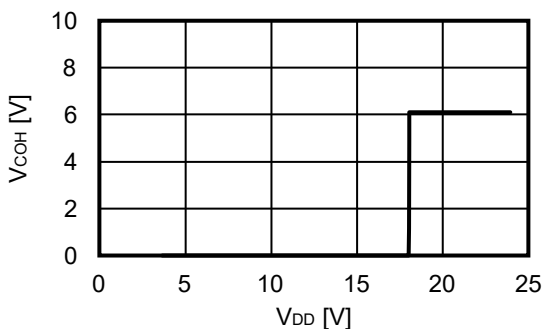


3.2 t_{RSD} vs. T_a

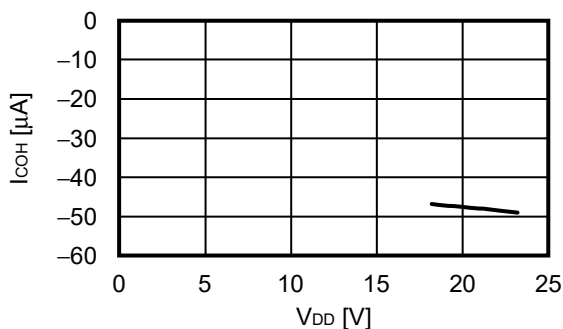


4. Output pin

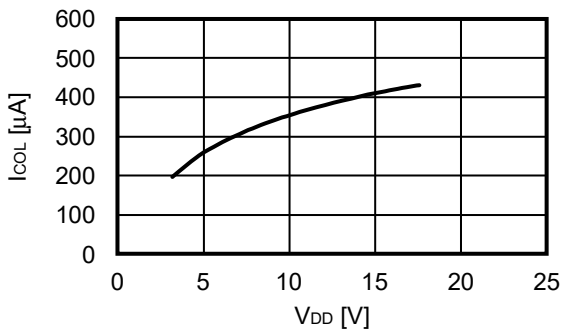
4.1 V_{COH} vs. V_{DD}



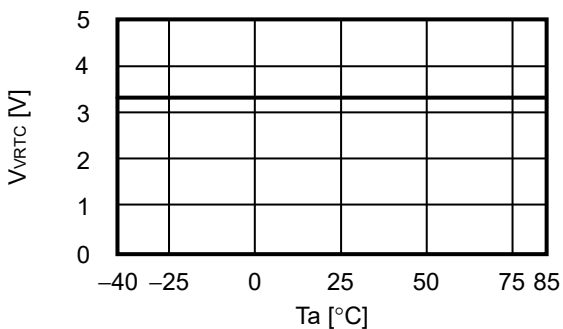
4.2 I_{COH} vs. V_{DD}



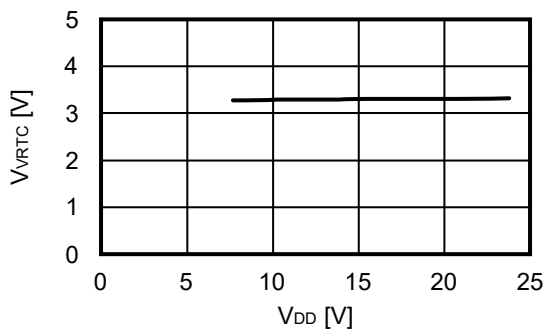
4.3 I_{COL} vs. V_{DD}



4.4 V_{VRTC} vs. T_a

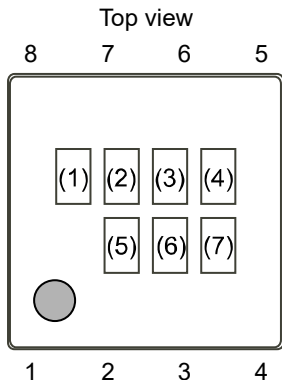


4.5 V_{VRTC} vs. V_{DD}



■ **Marking Specifications**

1. DFN-8(2020)A



- (1): Blank
- (2) to (4): Product code (Refer to **Product name vs. Product code**)
- (5) to (7): Lot number

Product name vs. Product code

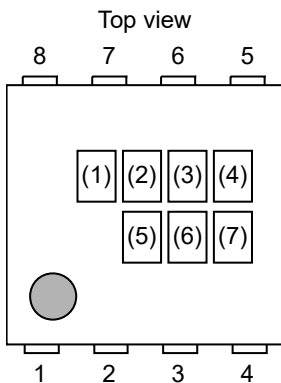
1.1 S-82K3 Series

Product name	Product code		
	(2)	(3)	(4)
S-82K3AAA-A8T8U	9	L	A
S-82K3AAB-A8T8U	9	L	B

1.2 S-82K4 Series

Product name	Product code		
	(2)	(3)	(4)
S-82K4AAA-A8T8U	9	L	R
S-82K4AAB-A8T8U	9	L	S

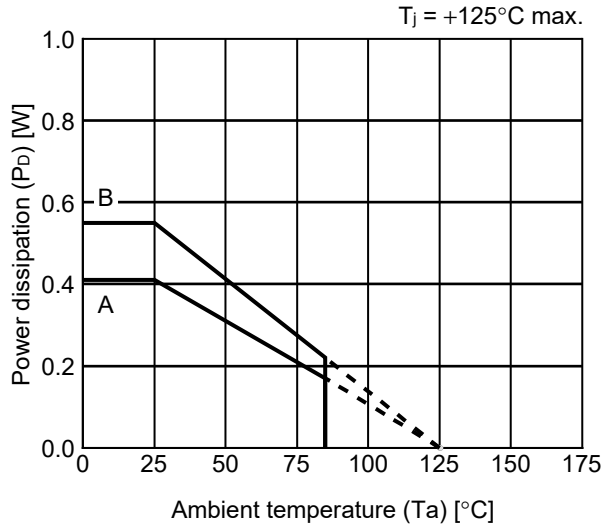
2. HSNT-8(1616)



- (1): Blank
- (2) ~ (4): Product code
- (5) ~ (7): Lot number

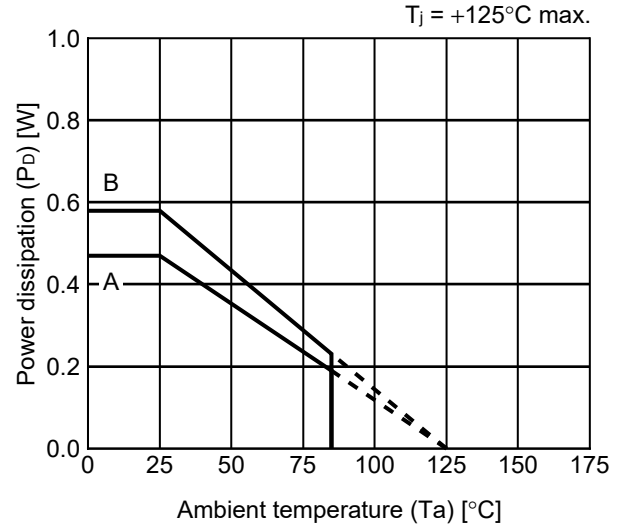
■ **Power Dissipation**

DFN-8(2020)A




Board	Power Dissipation (Pd)
A	0.41 W
B	0.55 W
C	–
D	–
E	–

HSNT-8(1616)

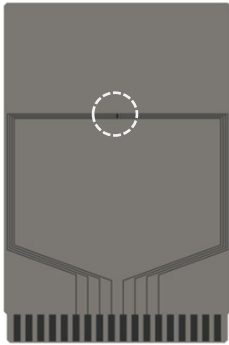


Board	Power Dissipation (Pd)
A	0.47 W
B	0.58 W
C	–
D	–
E	–

DFN-8(2020)A Test Board

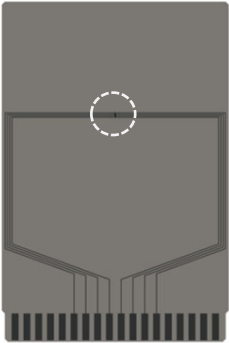
 IC Mount Area

(1) Board A



Item	Specification	
Size [mm]	114.3 x 76.2 x t1.6	
Material	FR-4	
Number of copper foil layer	2	
Copper foil layer [mm]	1	Land pattern and wiring for testing: t0.070
	2	-
	3	-
	4	74.2 x 74.2 x t0.070
Thermal via	-	

(2) Board B



Item	Specification	
Size [mm]	114.3 x 76.2 x t1.6	
Material	FR-4	
Number of copper foil layer	4	
Copper foil layer [mm]	1	Land pattern and wiring for testing: t0.070
	2	74.2 x 74.2 x t0.035
	3	74.2 x 74.2 x t0.035
	4	74.2 x 74.2 x t0.070
Thermal via	-	



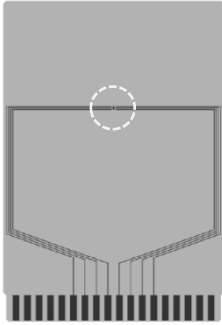
enlarged view

No. DFN8-E-Board-SD-1.0

HSNT-8(1616) Test Board

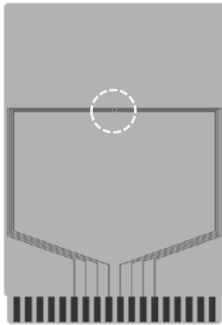
 IC Mount Area

(1) Board A



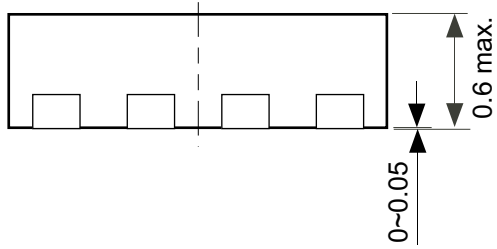
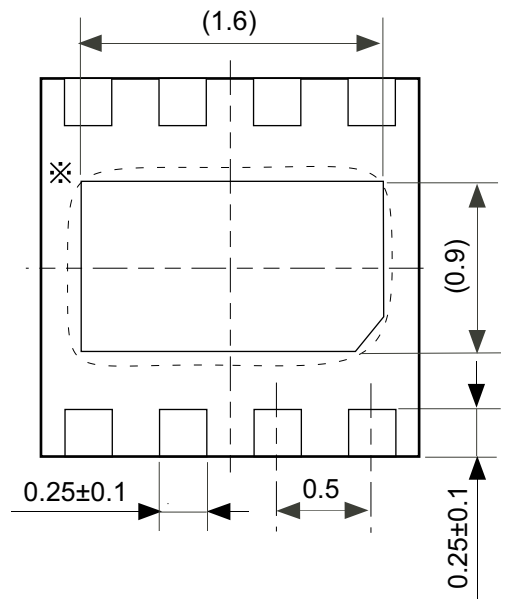
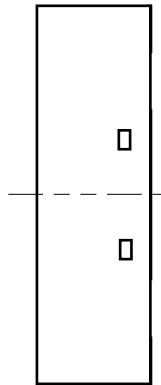
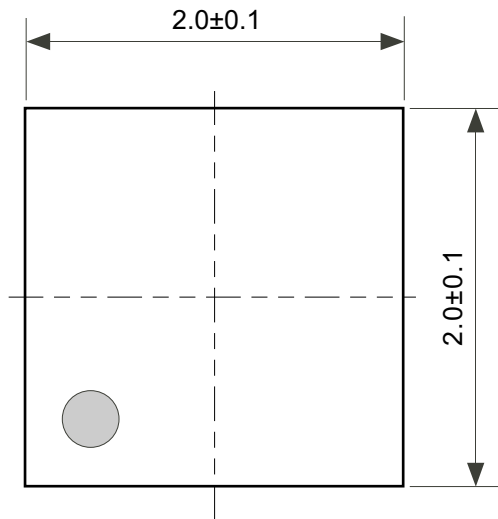
Item		Specification
Size [mm]		114.3 x 76.2 x t1.6
Material		FR-4
Number of copper foil layer		2
Copper foil layer [mm]	1	Land pattern and wiring for testing: t0.070
	2	-
	3	-
	4	74.2 x 74.2 x t0.070
Thermal via		-

(2) Board B



Item		Specification
Size [mm]		114.3 x 76.2 x t1.6
Material		FR-4
Number of copper foil layer		4
Copper foil layer [mm]	1	Land pattern and wiring for testing: t0.070
	2	74.2 x 74.2 x t0.035
	3	74.2 x 74.2 x t0.035
	4	74.2 x 74.2 x t0.070
Thermal via		-

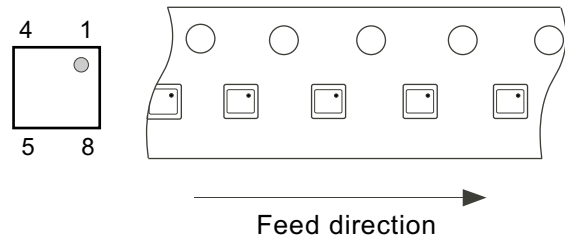
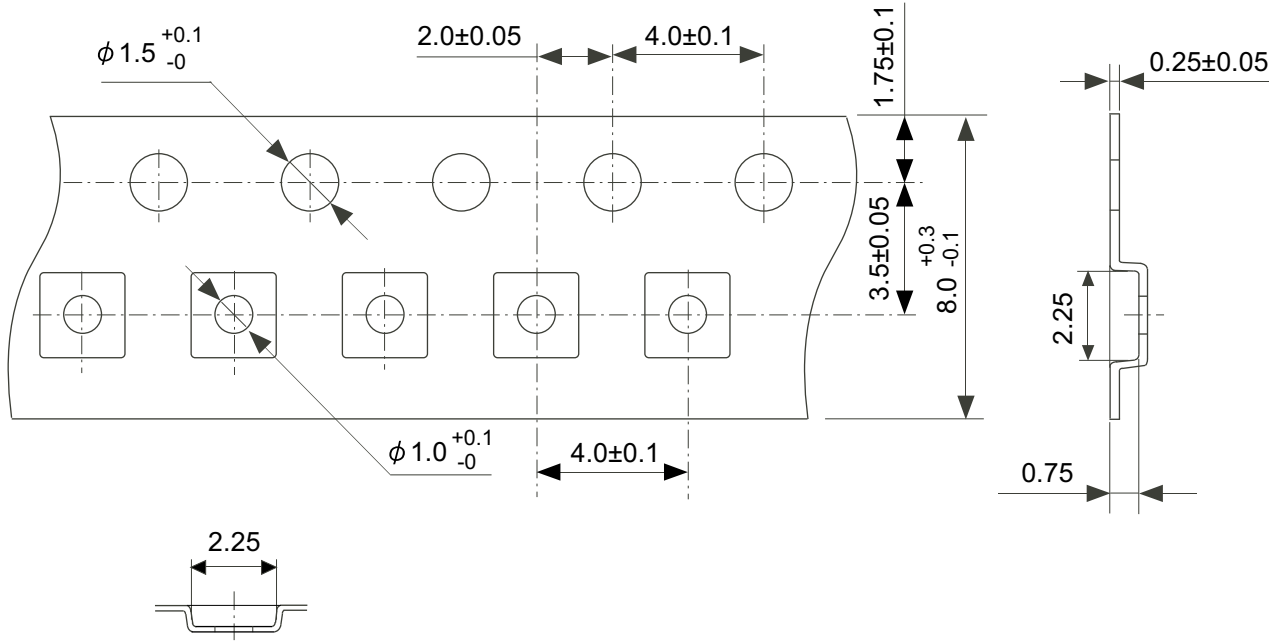
No. HSNT8-B-Board-SD-1.0



※ The heat sink of back side has different electric potential depending on the product. Confirm specifications of each product. Do not use it as the function of electrode.

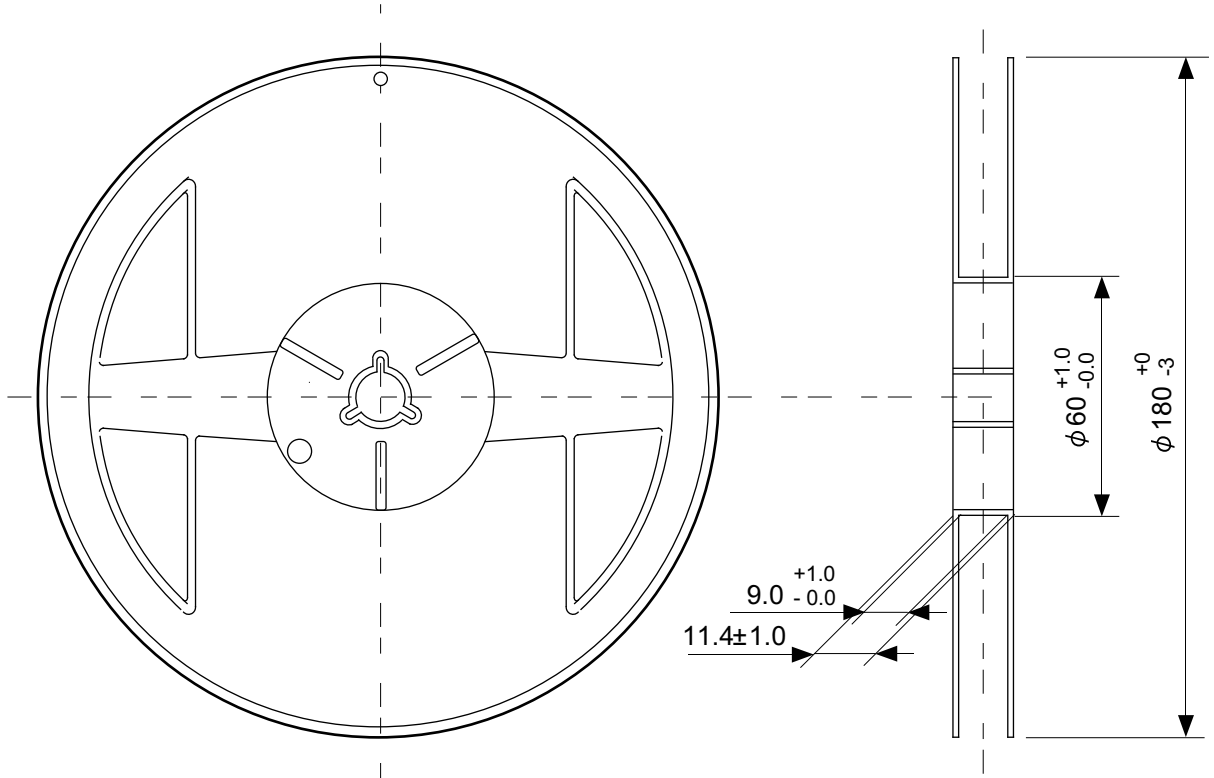
No. IB008-A-P-SD-1.0

TITLE	DFN-8-E-PKG Dimensions
No.	IB008-A-P-SD-1.0
ANGLE	
UNIT	mm
ABLIC Inc.	

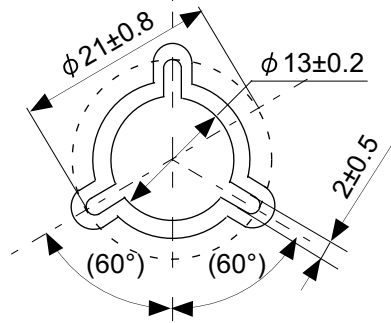


No. IB008-A-C-SD-1.0

TITLE	DFN-8-E-Carrier Tape
No.	IB008-A-C-SD-1.0
ANGLE	
UNIT	mm
ABLIC Inc.	



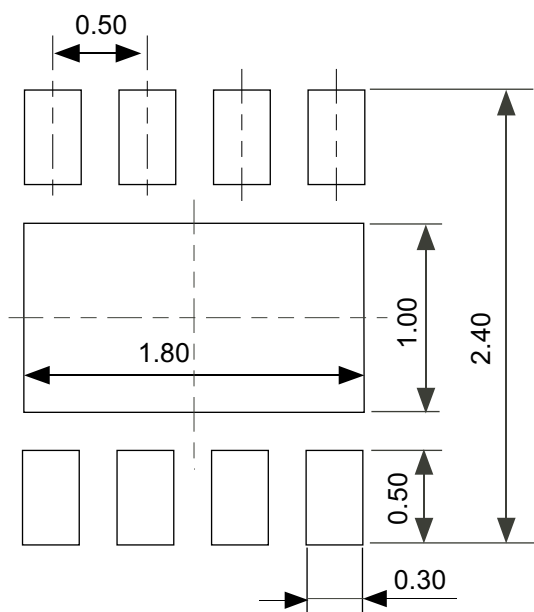
Enlarged drawing in the central part



No. IB008-A-R-SD-1.0

TITLE	DFN-8-E-Reel		
No.	IB008-A-R-SD-1.0		
ANGLE		QTY.	4,000
UNIT	mm		
ABLIC Inc.			

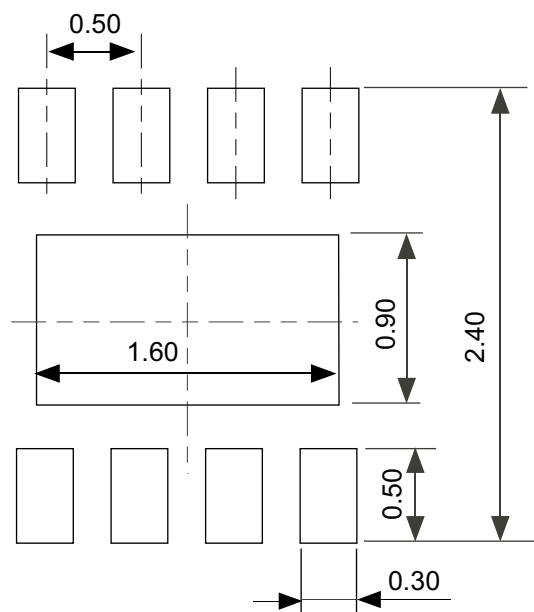
Land Pattern



Caution It is recommended to solder the heat sink to a board in order to ensure the heat radiation.

注意 放熱性を確保する為に、PKGの裏面放熱板(ヒートシンク)を基板に半田付けする事を推奨いたします。

Metal Mask Pattern

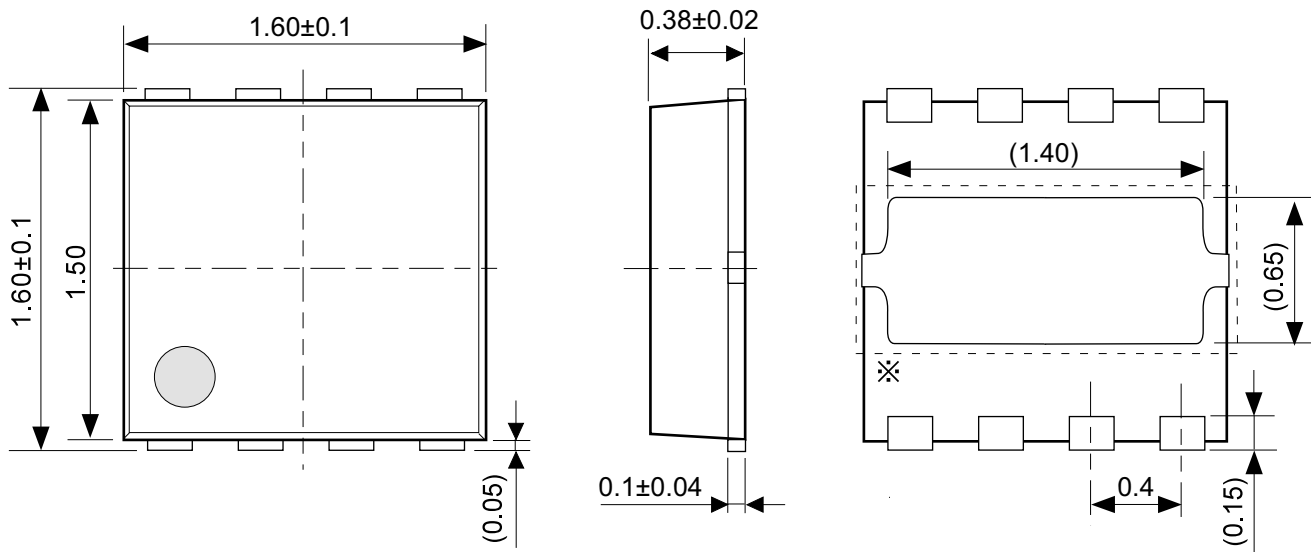


Caution ① Mask aperture ratio of the lead mounting part is 100%.
 ② Mask aperture ratio of the heat sink mounting part is 80%.
 ③ Mask thickness: t0.12 mm

注意 ①リード実装部のマスク開口率は100%です。
 ②放熱板実装のマスク開口率は80%です。
 ③マスク厚み : t0.12 mm

No. IB008-A-L-SD-1.0

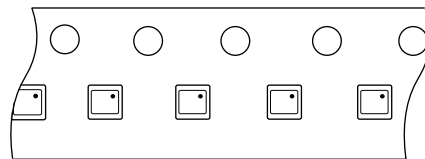
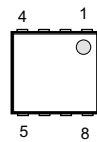
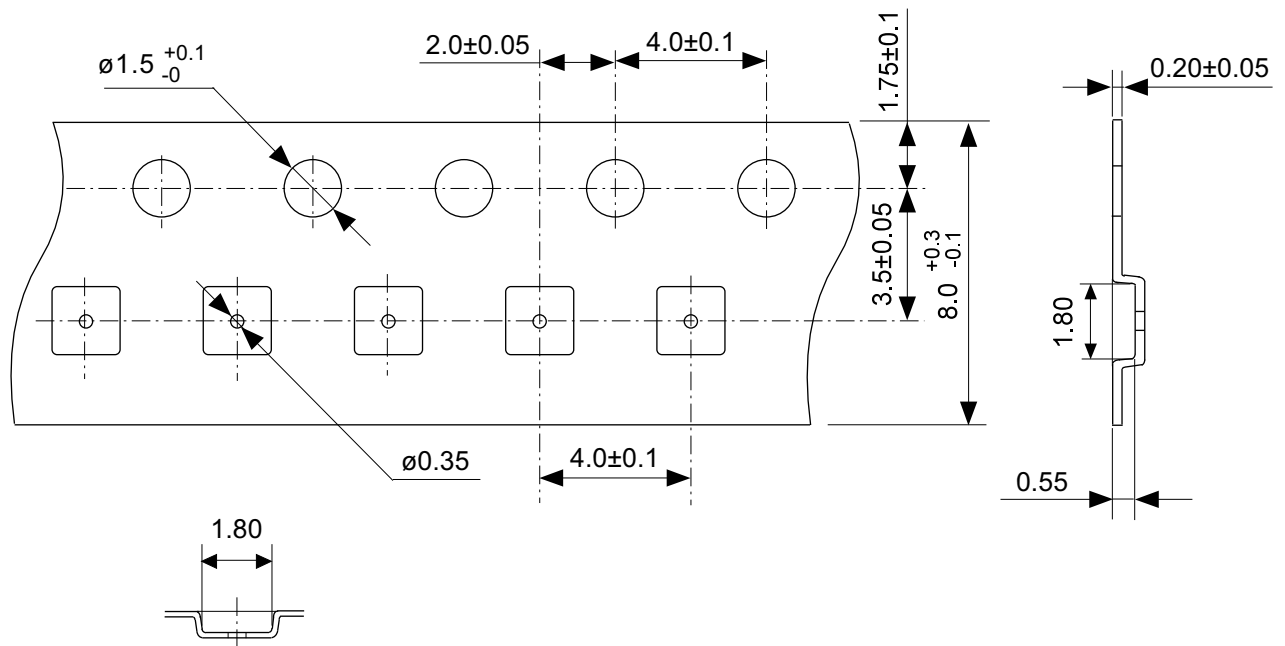
TITLE	DFN-8-E -Land Recommendation
No.	IB008-A-L-SD-1.0
ANGLE	
UNIT	mm
ABLIC Inc.	



※ The heat sink of back side has different electric potential depending on the product.
 Confirm specifications of each product.
 Do not use it as the function of electrode.

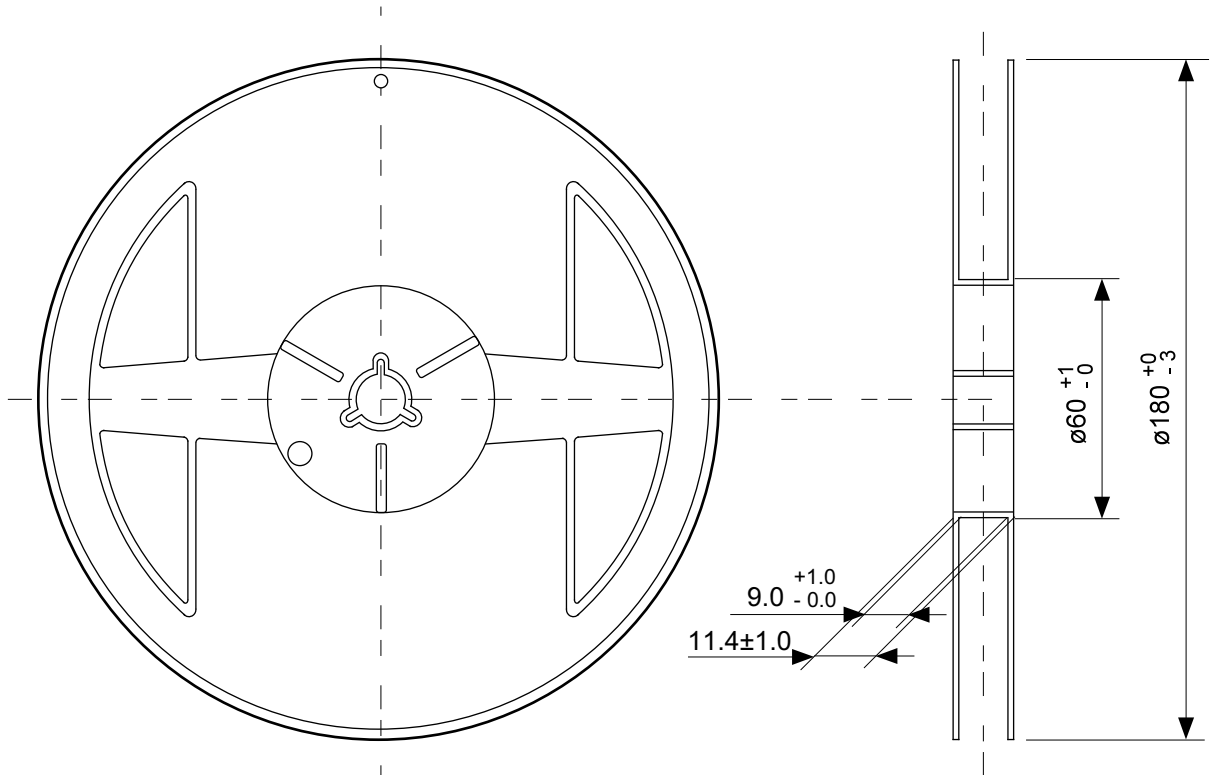
No. PY008-A-P-SD-1.0

TITLE	HSNT-8-B-PKG Dimensions
No.	PY008-A-P-SD-1.0
ANGLE	
UNIT	mm
ABLIC Inc.	

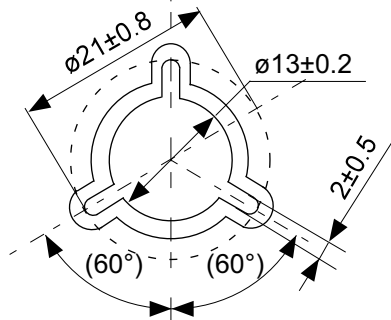


No. PY008-A-C-SD-1.0

TITLE	HSNT-8-B-Carrier Tape
No.	PY008-A-C-SD-1.0
ANGLE	
UNIT	mm
ABLIC Inc.	



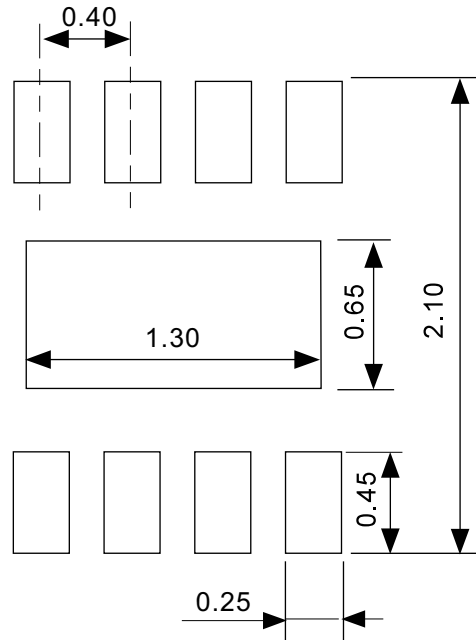
Enlarged drawing in the central part



No. PY008-A-R-SD-1.0

TITLE	HSNT-8-B-Reel		
No.	PY008-A-R-SD-1.0		
ANGLE		QTY.	5,000
UNIT	mm		
ABLIC Inc.			

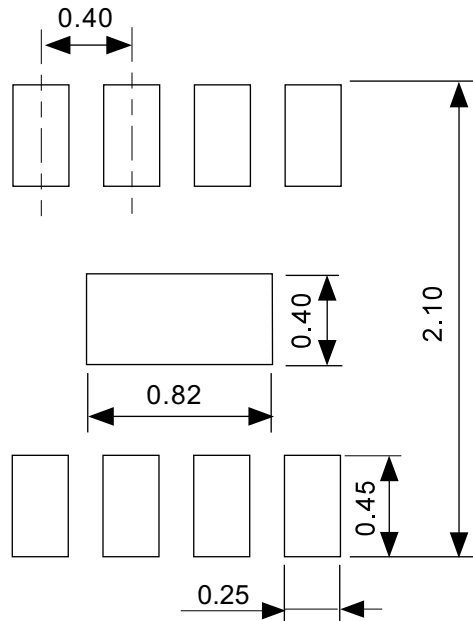
Land Pattern



Caution It is recommended to solder the heat sink to a board in order to ensure the heat radiation.

注意 放熱性を確保する為に、PKGの裏面放熱板(ヒートシンク)を基板に半田付けする事を推奨いたします。

Metal Mask Pattern



- Caution
- ① Mask aperture ratio of the lead mounting part is 100%.
 - ② Mask aperture ratio of the heat sink mounting part is 40%.
 - ③ Mask thickness: t0.12 mm

- 注意
- ①リード実装部のマスク開口率は100%です。
 - ②放熱板実装のマスク開口率は40%です。
 - ③マスク厚み : t0.12 mm

No. PY008-A-L-SD-1.0

TITLE	HSNT-8-B -Land Recommendation
No.	PY008-A-L-SD-1.0
ANGLE	
UNIT	mm
ABLIC Inc.	

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2.4-2019.07